

a sole plate interposed between a second face of the printed circuit card and the radiator base,

a plurality of pads integral with the sole plate, said pads being made of a thermally conductive material and being housed in holes, made in the printed circuit card, in order to pass through the printed circuit card over substantially its whole thickness,

wherein the sole plate is made of a same material or one with a similar coefficient of expansion and/or thermal conductivity as the base box and wherein the box enclosing at least one electronic component and the plurality of pads are soldered to the printed circuit card, in order to solder the box enclosing at least one electronic component to the plurality of pads.

15. (Amended) The assembly according to claim 9, wherein the sole plate is soldered to the printed circuit card.

16. (Amended) The assembly according to claim 15, wherein the sole plate has through-holes for discharging residual air possibly trapped in the solder.

Please add new claims 17-18 as follows:

--17. The assembly according to claim 9, wherein the box is a box enclosing at least one surface-mount electronic power component.--

--18. An assembly comprising:

a base forming a radiator,

a printed circuit card having a first face which supports at least one box enclosing at least one electronic component and having a box base adjacent to the first face,

a sole plate interposed between a second face of the printed circuit card and the radiator base,